

2SK2008

Silicon N Channel MOS FET

REJ03G0992-0200

(Previous: ADE-208-1340)

Rev.2.00 Sep 07, 2005

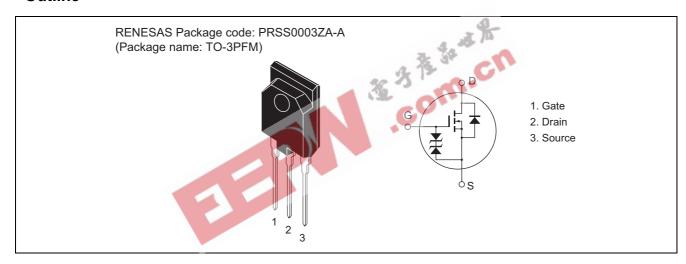
Application

High speed power switching

Features

- Low on-resistance
- High speed switching
- Low drive current
- No Secondary Breakdown
- Suitable for Switching regulator, DC DC converter, motor control

Outline



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Ratings	Unit
Drain to source voltage	V _{DSS}	250	V
Gate to source voltage	V_{GSS}	±30	V
Drain current	I _D	20	А
Drain peak current	I _{D(pulse)} *1	80	А
Body to drain diode reverse drain current	I _{DR}	20	А
Channel dissipation	Pch*2	60	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. PW \leq 10 μ s, duty cycle \leq 1 %

2. Value at Tc = 25°C

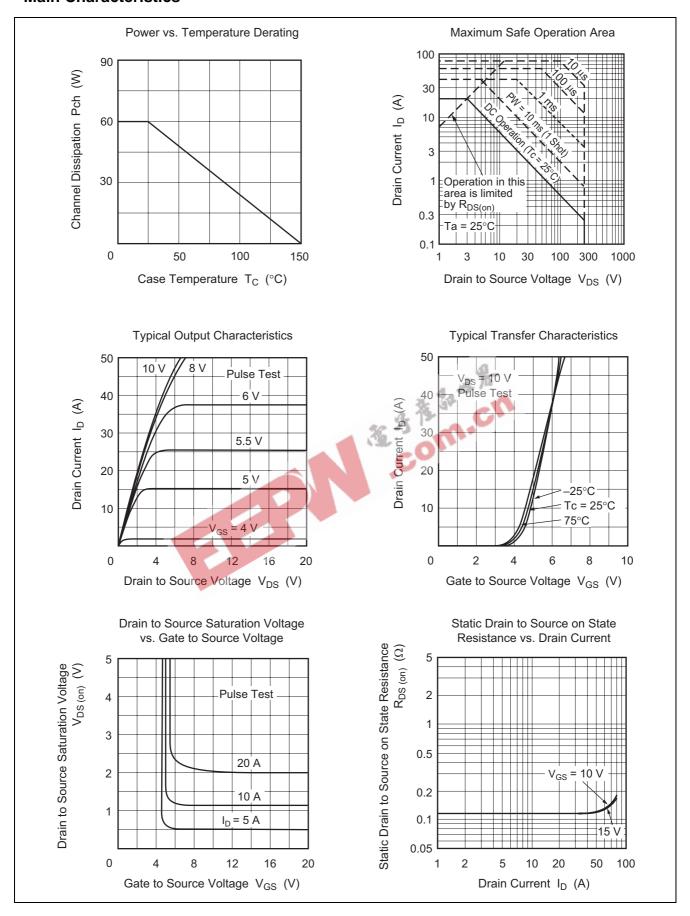
Electrical Characteristics

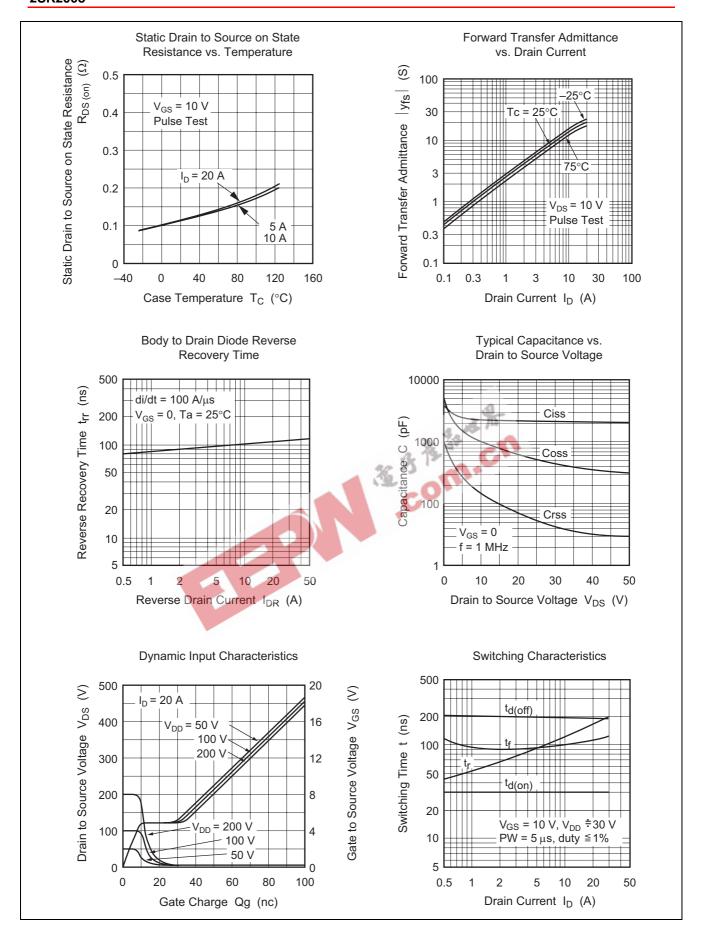
 $(Ta = 25^{\circ}C)$

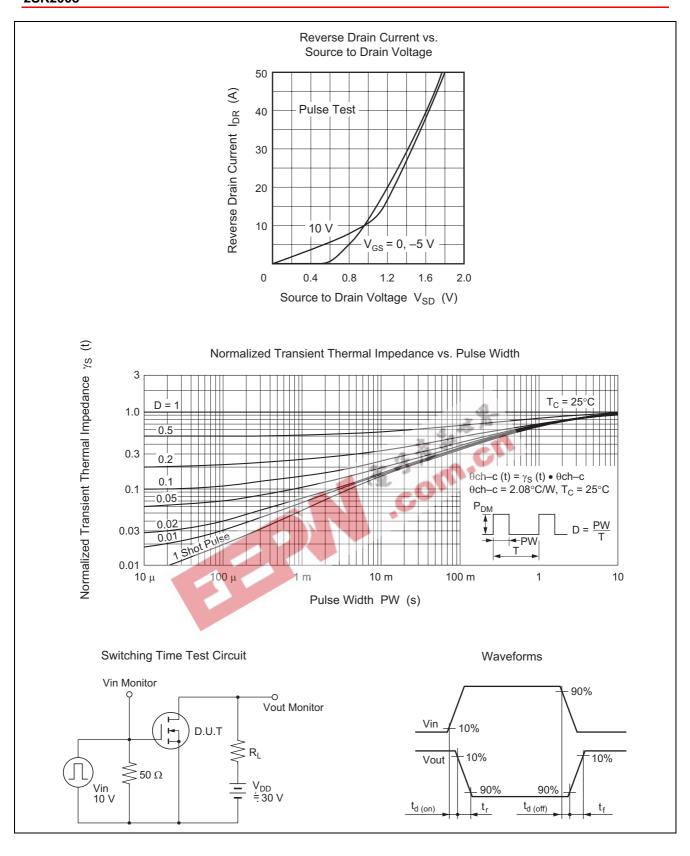
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	250	_	_	V	$I_D = 10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	$V_{(BR)GSS}$	±30	-	_	V	$I_G = \pm 100 \; \mu A, \; V_{DS} = 0$
Gate to source leak current	I_{GSS}	_	-	±10	μΑ	$V_{GS} = \pm 25 \text{ V}, V_{DS} = 0$
Zero gate voltage drain current	I _{DSS}	_	-	250	μΑ	$V_{DS} = 200 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	2.0	_	3.0	V	$I_D = 1 \text{ mA}, V_{DS} = 10 \text{ V}$
Static drain to source on state	R _{DS(on)}	_	0.12	0.15	Ω	$I_D = 10 \text{ A}, V_{GS} = 10 \text{ V}^{*3}$
resistance			18	3) · 4		
Forward transfer admittance	y _{fs}	9.0	14	~O)	S	$I_D = 10 \text{ A}, V_{DS} = 10 \text{ V}^{*3}$
Input capacitance	Ciss	4	2340		pF	$V_{DS} = 10 \text{ V}, V_{GS} = 0,$
Output capacitance	Coss	, 	1000	_	рF	f = 1 MHz
Reverse transfer capacitance	Crss	7	160	_	pF	
Turn-on delay time	t _{d(on)}		30	_	ns	$I_D = 10 \text{ A}, V_{GS} = 10 \text{ V},$
Rise time	t _r	_	125	_	ns	$R_L = 3 \Omega$
Turn-off delay time	t _{d(off)}	_	190	_	ns	
Fall time	t _f	_	100	_	ns	
Body to drain diode forward voltage	V _{DF}	_	1.2	_	V	$I_F = 20 \text{ A}, V_{GS} = 0$
Body to drain diode reverse	t _{rr}	_	120	_	ns	$I_F = 20 \text{ A}, V_{GS} = 0,$
recovery time						$di_{F} / dt = 100 A / \mu s$

Note: 3. Pulse Test

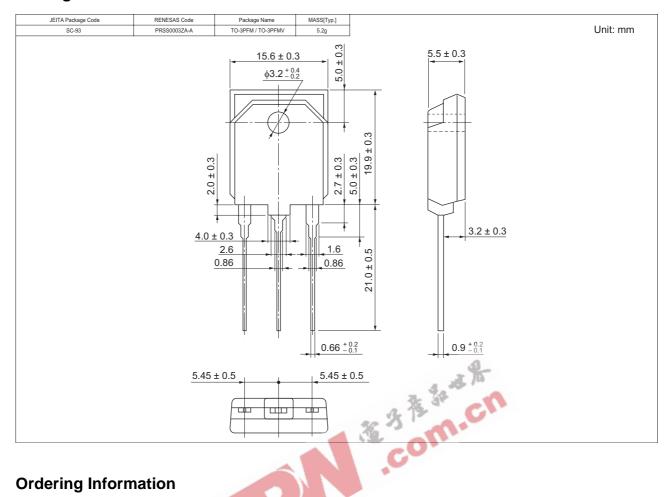
Main Characteristics







Package Dimensions



Ordering Information

Part Name	Quantity		Shipping Container
2SK2008-E	360 pcs	Box (Tube)	

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